



Material Content Data Sheet



Sales Product Name	TLE7244SL			Issued		28. August 2013		
MA#	MA000982072							
Package	PG-SSOP-24-7			Weight*		147.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.128	3.49	3.49	34853	34853
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		423	
	non noble metal	iron	7439-89-6	1.245	0.85		8464	
	non noble metal	copper	7440-50-8	50.568	34.37	35.27	343671	352664
wire	noble metal	gold	7440-57-5	0.769	0.52	0.52	5224	5224
encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1160	
	plastics	epoxy resin	-	7.854	5.34		53377	
	inorganic material	silicondioxide	60676-86-0	77.344	52.55	58.01	525648	580185
leadfinish	non noble metal	tin	7440-31-5	1.680	1.14	1.14	11416	11416
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2482	2482
glue	plastics	acrylic resin	-	0.426	0.29		2899	
	noble metal	silver	7440-22-4	1.512	1.03	1.32	10277	13176
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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